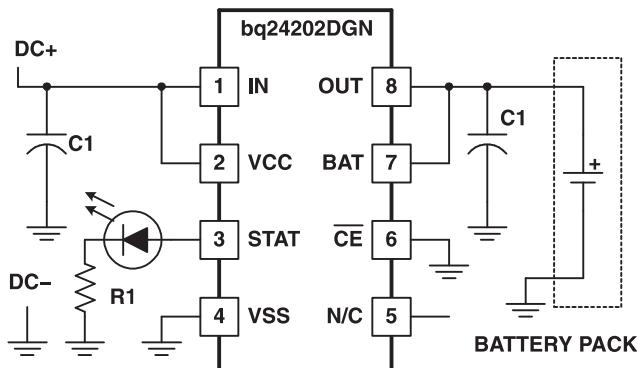


SINGLE-CHIP LI-ION AND LI-POL CHARGE MANAGEMENT IC FOR CURRENT-LIMITED APPLICATIONS

FEATURES

- Designed Specifically to Work With Current-Limited Wall Supplies
- Ideal for Low Dropout Charger Design for Single-Cell Li-Ion Packs With Coke or Graphite Anodes
- Integrated PowerFET for 500 mA
- Integrated Voltage Regulation With 0.5% Accuracy
- Battery Insertion and Removal Detection
- Charge Termination by Minimum Current and Time
- Pre-Charge Conditioning With Safety Timer
- Sleep Mode for Low-Power Consumption
- Charge Status Output for LED or Host Processor Interface Indicates
- Charge-in-Progress, Charge Completion, and Fault Conditions
- Optional Temperature Monitoring Before and During Charge
- Small, 8-Pin Power-Pad MSOP Package

TYPICAL APPLICATION



DESCRIPTION

The bq2420x series are simple Li-Ion linear charge management devices targeted at low-cost and space limited charger applications. The bq2420x series offer integrated powerFET, high-accuracy voltage regulation, temperature monitoring, charge status, and charge termination, in a single monolithic device.

The bq2420x is designed to work with a current-limited wall-mount transformer and therefore does not provide any current regulation. However, these devices offer a fixed internal current limit to prevent damage to the internal powerFET. A time-limited pre-conditioning phase is provided to condition deeply discharged cells. Once the battery reaches the charge voltage, the high accuracy voltage regulation loop takes over and completes the charge cycle. Charge is terminated based on minimum current. An internal charge timer provides a backup safety for charge termination.

Other standard features include an automatic sleep mode activated when V_{CC} falls below the battery voltage and a recharge feature activated when the battery voltage falls below the V_{RCH} threshold.

In addition to the standard features, the core product provides two additional enhancements: temperature monitoring and status display. The temperature-sense circuit continuously measures battery temperature using an external thermistor and inhibits charge until the battery temperature is within the user-defined thresholds. The STAT pin indicates three conditions of operation of the charger. These conditions are *charge-in-progress*, *charge complete*, and *fault*. This output can be used to drive an LED or an interface to a microcontroller.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

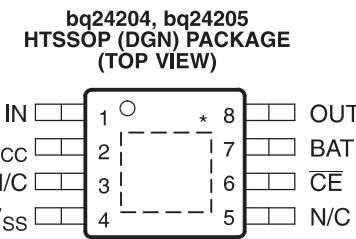
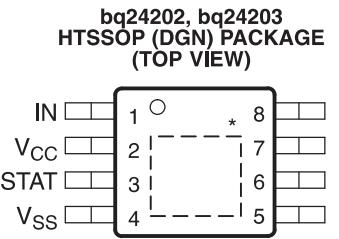
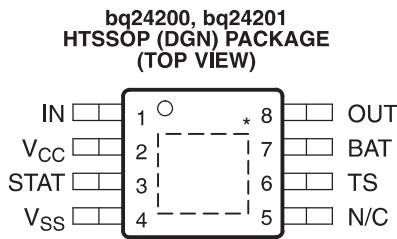


These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

AVAILABLE OPTIONS

| T _J | CHARGE REGULATION VOLTAGE | OPTIONAL FUNCTIONS | MARKING | PACKAGED DEVICES (DGN) ⁽¹⁾ |
|----------------|---------------------------------|-----------------------|---------|---------------------------------------------|
| -40°C to 125°C | 4.2 V | STAT and TS | AZC | bq24200DGN |
| | 4.1 V | STAT and TS | AZD | bq24201DGN |
| | 4.2 V | STAT | AZE | bq24202DGN |
| | 4.1 V | STAT | AZF | bq24203DGN |
| | 4.2 V | — | AZG | bq24204DGN |
| | 4.1 V | — | AZI | bq24205DGN |

(1) The DGN package is available taped and reeled. Add TR suffix to device type (e.g. bq24200DGNTR) to order. Quantities 2500 devices per reel.



TERMINAL FUNCTIONS

| NAME | TERMINAL | | | I/O | DESCRIPTION | | |
|-----------------|--------------------|--------------------|--------------------|-----|--------------------------------------|--|--|
| | NO. | | | | | | |
| | bq24200 bq24201 | bq24202 bq24203 | bq24204 bq24205 | | | | |
| BAT | 7 | 7 | 7 | I | Battery voltage sense input | | |
| CE | — | 6 | 6 | I | Charge enable input (active low) | | |
| IN | 1 | 1 | 1 | I | Charge input voltage | | |
| N/C | 5 | 5 | 3, 5 | — | No connection. Must be left floating | | |
| OUT | 8 | 8 | 8 | O | Charge current output | | |
| STAT | 3 | 3 | — | O | Charge status output | | |
| TS | 6 | — | — | I | Temperature sense input | | |
| V _{CC} | 2 | 2 | 2 | I | V _{CC} input | | |
| V _{SS} | 4 | 4 | 4 | — | Ground input | | |

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

| | | VALUE | UNIT |
|-------------------------------------------------------|----------------------------|------------|------|
| Supply voltage (V _{CC} with respect to GND) | | 16.5 | V |
| Input voltage, IN, STAT, TS (all with respect to GND) | | 16.5 | V |
| Input voltage, BAT, OUT (all with respect to GND) | | 7 | V |
| Output sink/source current (STAT) | | 15 | mA |
| T _{STG} | Storage temperature range | –65 to 150 | °C |
| T _J | Junction temperature range | –40 to 125 | °C |
| Lead temperature (soldering, 10 sec) | | 300 | °C |

(1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

DISSIPATION RATINGS

| PACKAGE | THERMAL IMPEDANCE JUNCTION-TO-AMBIENT (θ _{JA}) | THERMAL IMPEDANCE JUNCTION-TO-CASE (θ _{JC}) | T _A ≤ 25°C POWER RATING | DERATING FACTOR ABOVE T _A = 25°C |
|--------------------------|-------------------------------------------------------------|----------------------------------------------------------|---------------------------------------|------------------------------------------------|
| 8 Pin DGN ⁽¹⁾ | 57.20°C/W | 4.4°C/W | 1.75 W | 0.017 W/°C |

(1) This data is based on using JEDEC High-K board and topside traces, top and bottom thermal pad (2 mm × 3 mm), internal 1 oz. power and ground planes, four thermal via underneath the die connecting to ground plane.

RECOMMENDED OPERATING CONDITIONS

| | | MIN | MAX | UNIT |
|-----------------|--------------------------------------|-------------------------|------|------|
| V _{CC} | Supply voltage | V _(LOWV-MIN) | 13.5 | V |
| V _{IN} | Input voltage | V _(LOWV-MIN) | 13.5 | V |
| T _J | Operating junction temperature range | –40 | 125 | °C |

ELECTRICAL CHARACTERISTICS

over 0°C ≤ T_J ≤ 125°C and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------------------------------------------|-----------------------------------------------------------------------------------------------------------|-----|-----|-----|------|
| I _{CC(VCC)} V _{CC} Current | V _{CC} > V _{CC(min)} | | 1.7 | 2.5 | mA |
| I _{CC(SLP)} Sleep current | Sum of currents into OUT and BAT pins, V _{CC} < V _(SLP) , 0°C ≤ T _J ≤ 85°C | | | 5 | μA |
| | Sum of currents into OUT and BAT pins, V _{CC} < V _(SLP) | | | 10 | μA |
| I _{CC(STDBY)} Standby current | Sum of currents into V _{CC} , IN and TS pins, (V _{CC} –V _{I(TS)}) ≤ 300 mV | | | 1 | mA |
| I _{IB(BAT)} Input bias current on BAT pin | | | | 1 | μA |
| I _{IB(TS)} Input bias current on TS pin | 0.1 × V _{CC} ≤ V _{I(TS)} ≤ 0.8 × V _{CC} | | | 1 | μA |

VOLTAGE REGULATION

V_{O(REG) + V(DO-MAX)} ≤ V_{CC}, I_{(TERM) < I_{O(OUT)}} ≤ 500 mA, over 0°C ≤ T_J ≤ 125°C and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-----------------------------------------------------------------------------|----------------------------------------------------------------------------------------------|--------|------|--------|------|
| V _{O(REG)} Output voltage | V _{O(REG) + V(DO-MAX)} ≤ 10 V, I _{(TERM) < I_{O(OUT)}} ≤ 250 mA | 4.0795 | 4.10 | 4.1205 | V |
| | | 4.05 | 4.10 | 4.15 | V |
| | V _{O(REG) + V(DO-MAX)} ≤ 10 V, I _{(TERM) < I_{O(OUT)}} ≤ 250 mA | 4.1790 | 4.20 | 4.2210 | V |
| | | 4.15 | 4.20 | 4.25 | V |
| V _(DO) Dropout voltage (V _(IN) – V _(OUT)) | V _{O(REG) + V(DO-MAX)} ≤ V _{CC} , I _{O(OUT)} = 500 mA | 200 | 350 | 500 | mV |

OUTPUT CURRENT

over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------|----------------------------|--------------------|-----|-----|------|
| $I_{O(OUT)}$ | Output current | | | 500 | mA |
| $I_{(SC)}$ | Short-circuit trip current | See ⁽¹⁾ | 1 | 1.6 | A |

(1) Assured by design, not production tested.

PRE-CHARGE CURRENT REGULATION

over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------|---------------------------------------------------------|-----|------|-----|---------------|
| $I_{(PRECHG)}$ | $V_{I(BAT)} < V_{(LOWV)}$, $t < t_{(30\text{min})}$ | 10 | 13.5 | 19 | mA |
| $I_{(DETECT)}$ | $V_{I(BAT)} < 2.5 \text{ V}$, $t < t_{(30\text{min})}$ | 160 | 210 | 300 | μA |

CHARGE TERMINATION DETECTION

over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------|--------------------------|-----|------|-----|------|
| $I_{(TAPER)}$ | $V_{I(BAT)} > V_{(RCH)}$ | 21 | 25.5 | 31 | mA |
| $I_{(TERM)}$ | $V_{I(BAT)} > V_{(RCH)}$ | 0.8 | 1.1 | 1.4 | mA |

TEMPERATURE COMPARATOR

over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------|-----------------------------|----------------|------|-----|------|
| $V_{(TS1)}$ | Lower temperature threshold | TS pin voltage | | 30 | %VCC |
| $V_{(TS2)}$ | Upper temperature threshold | TS pin voltage | | 60 | %VCC |
| Accuracy | | | -0.7 | 0.7 | %VCC |
| Hysteresis | | | 1 | | %VCC |

LOW VOLTAGE BATTERY THRESHOLD

over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------|------------------------------------------------------|-----|------|-----|------|
| $V_{(LOWV)}$ | $0^{\circ}\text{C} \leq T_J \leq 85^{\circ}\text{C}$ | 2.8 | 2.95 | 3.1 | V |
| | | 2.8 | 3.0 | 3.2 | V |

BATTERY RECHARGE THRESHOLD

over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------------------------------------------------------------|-----------------|------------------------|----------------------|------------------------|------|
| Recharge threshold, V_{RCH} (typically 100 mV below regulation) | | $V_{O(REG)}$ -0.115 | $V_{O(REF)}$ -0.1 | $V_{O(REG)}$ -0.085 | V |

STAT OUTPUT

$V_{cc} \geq V_{O(REG)}$, over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------|-----------------------|-----|-----|----------------|------|
| $V_{OL(STAT)}$ | $I_O = 10 \text{ mA}$ | | | 0.5 | V |
| $V_{OH(STAT)}$ | $I_O = -5 \text{ mA}$ | | | $V_{cc} - 1.5$ | V |

CE

 over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|--------------------------------------|---------------------------|------------|-----|------------|------|
| $V_{IL(CE)}$ Input (low) voltage | $I_{IL} = 5 \mu\text{A}$ | 0 | | $V_{CC}-1$ | V |
| $V_{IH(CE)}$ Input (high) voltage | $I_{IH} = 20 \mu\text{A}$ | $V_{CC}-0$ | .3 | | V |

TIMERS

 over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|---------------------------------------------------|-----------------|-------|-------|-------|------|
| $t_{(PRECH)}$ Pre-charge and taper timer G) | | 1,548 | 2,065 | 2,581 | sec |
| $t_{(TAPER)}$ Taper timer | | 1,548 | 2,065 | 2,581 | sec |
| $t_{(CHG)}$ Charge timer | | 9,292 | 12,38 | 15,48 | sec |
| | | 9 | | 6 | |

SLEEP COMPARATOR

 over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|-------------------------------------|-------------------------------------------------|----------------------|-----|-----|------|
| $V_{(SLP)}$ Sleep-mode threshold | $2.3 \text{ V} \leq V_{I(BAT)} \leq V_{O(REG)}$ | $V_{(BAT)}$ -10mV | | | V |

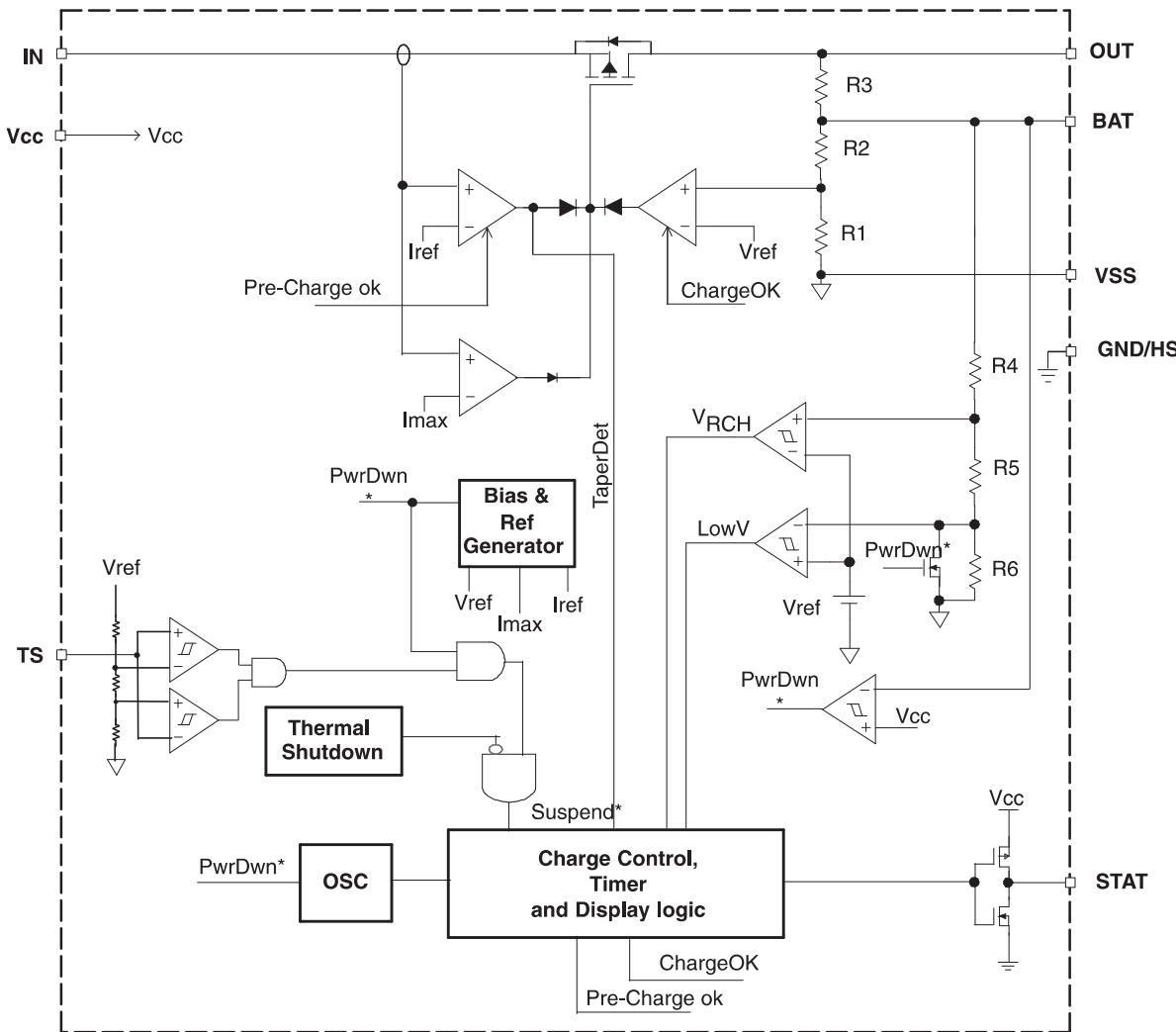
POWER-ON-RESET AND V_{IN} RAMP RATE

 over $0^{\circ}\text{C} \leq T_J \leq 125^{\circ}\text{C}$ and supply voltage range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP | MAX | UNIT |
|----------------------------|-----------------|-----|-----|--------------------|------------------------|
| V_{POR} POR threshold | See (1) | 2.3 | 2.4 | 2.5 | V |
| Slew rate | See (1) | 5 | | 5×10^{-5} | $\text{V}/\mu\text{s}$ |

(1) Ensured by design, not production tested.

FUNCTIONAL BLOCK DIAGRAM



DETAILED DESCRIPTION

IN: This pin is connected to the source of the internal P-channel powerFET.

OUT: This pin is connected to the drain of the internal P-channel powerFET.

Battery voltage sense (BAT): Voltage sense-input tied directly to the positive side of the battery.

Temperature sense input (TS): Input for an external battery-temperature monitoring circuit.

Charge status output (STAT): High-impedance indication of various charge conditions.

Supply voltage input (VCC): Power supply input

TYPICAL CHARACTERISTICS

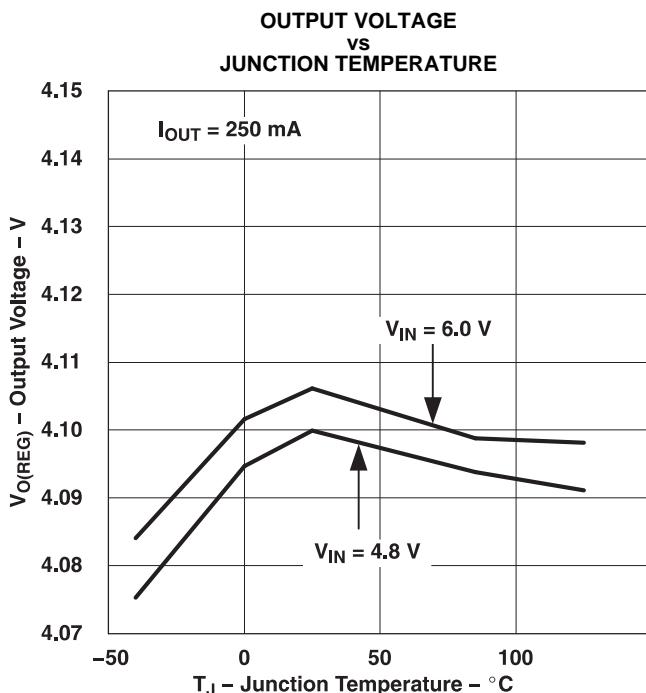


Figure 1.

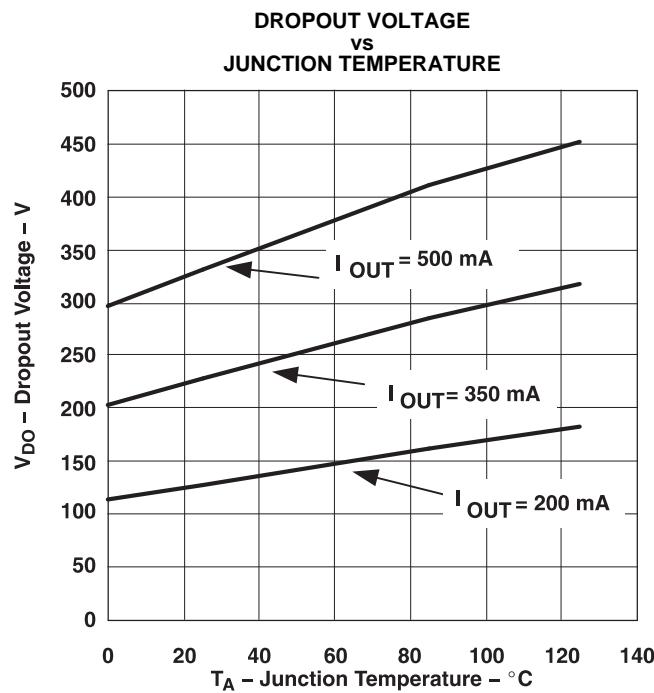


Figure 2.

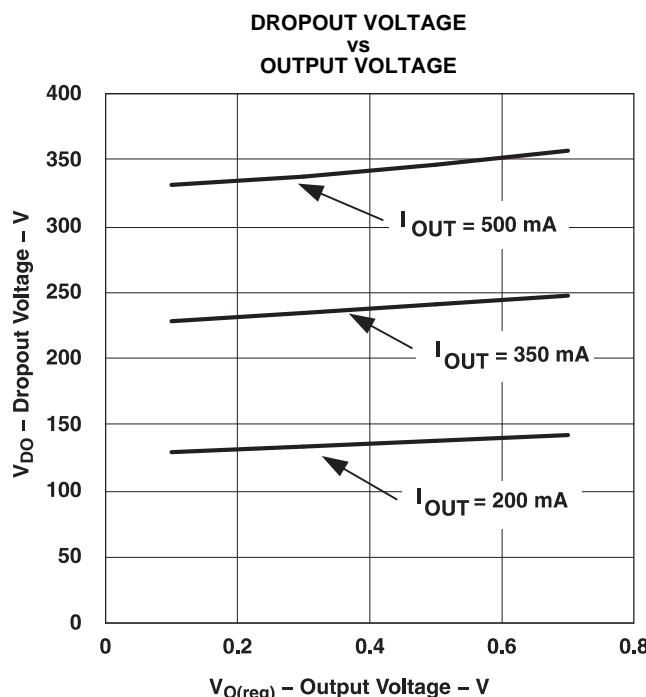


Figure 3.

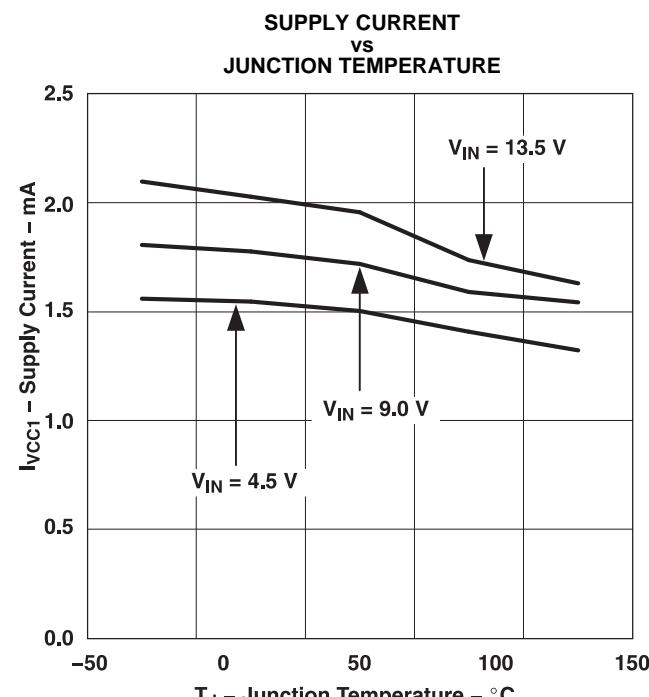


Figure 4.

APPLICATION INFORMATION

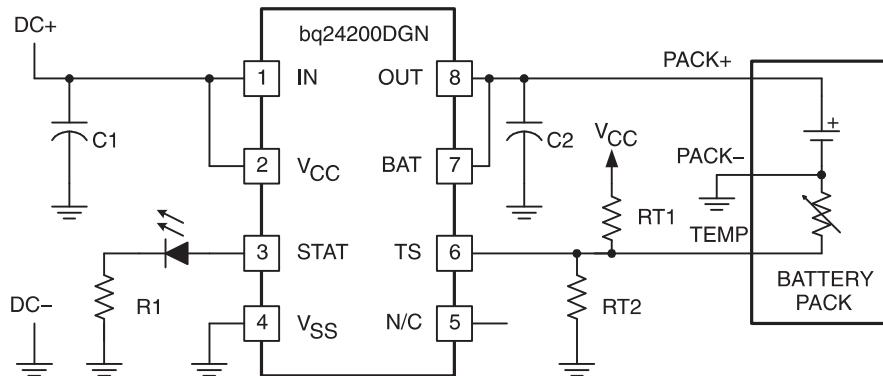


Figure 5. Low Dropout Single-Cell Li-Ion/Li-Pol Charger

FUNCTIONAL DESCRIPTION

The bq2420x supports a precision Li-Ion or Li-Pol charging system suitable for single-cells with either coke or graphite anodes. Figure 5 shows an application schematic and Figure 6 shows the typical charge profile.

TEMPERATURE QUALIFICATION (bq24200 and bq24202 only)

The bq24200 and bq24201 continuously monitors battery temperature by measuring the voltage between the TS and VSS pins. A negative- or a positive-temperature coefficient thermistor (NTC, PTC) and an external voltage divider typically develop this voltage (see Figure 5). The bq24200 and bq24201 compare this voltage against the internal $V_{(TS1)}$ and $V_{(TS2)}$ thresholds to determine if charging is allowed (see Figure 7). The temperature sensing circuit is immune to any fluctuation in Vcc since both the external voltage divider and the internal thresholds are referenced to Vcc.

Once a temperature outside the $V_{(TS1)}$ and $V_{(TS2)}$ thresholds is detected the bq24200 and bq24201 immediately suspend the charge. The bq24200 and bq24201 suspend the charge by turning off the power FET and holding the timer value (i.e., timers are NOT reset). Charge is resumed when the temperature returns to the normal range.

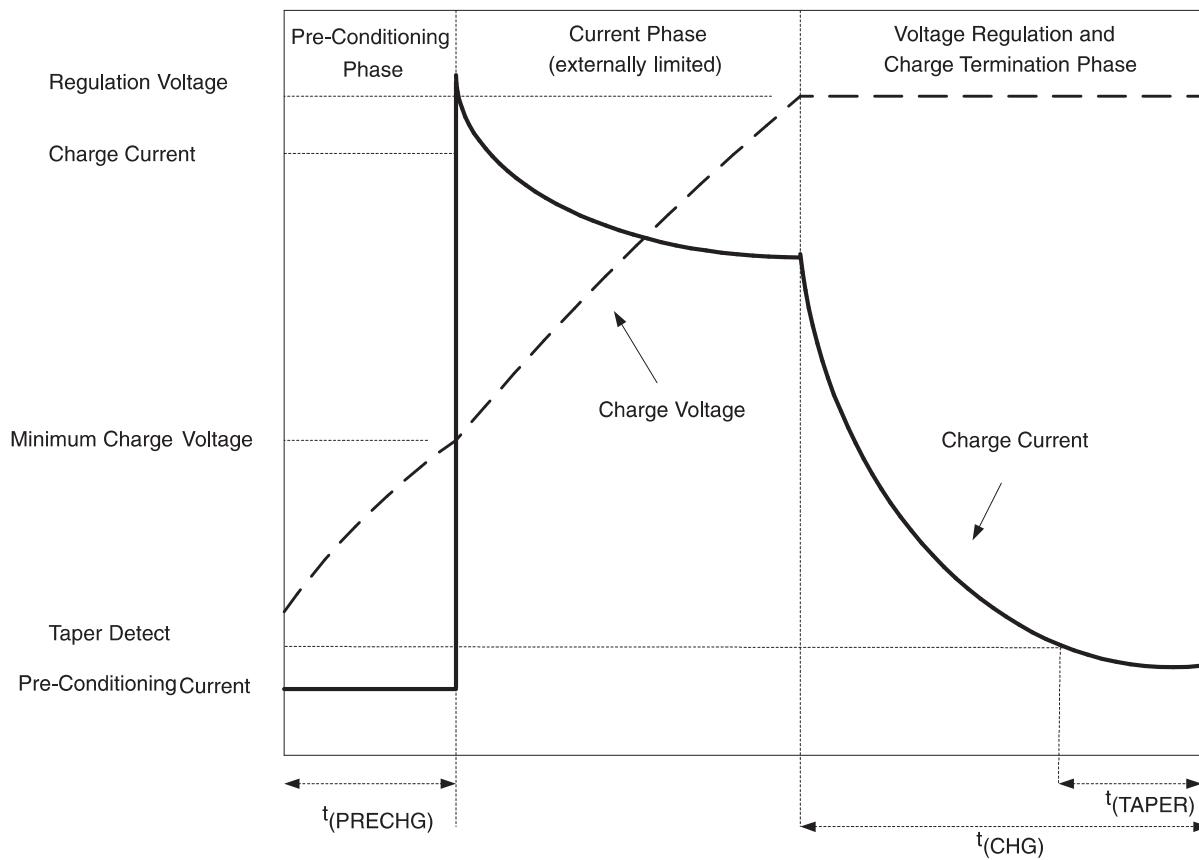


Figure 6. Typical Charge Profile

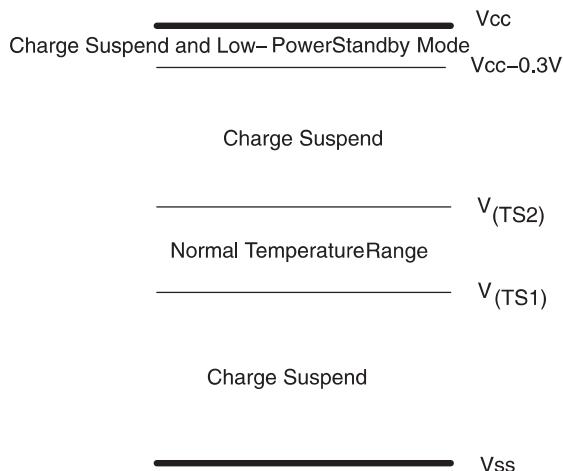


Figure 7. TS Pin Thresholds

OPERATIONAL FLOW DIAGRAM

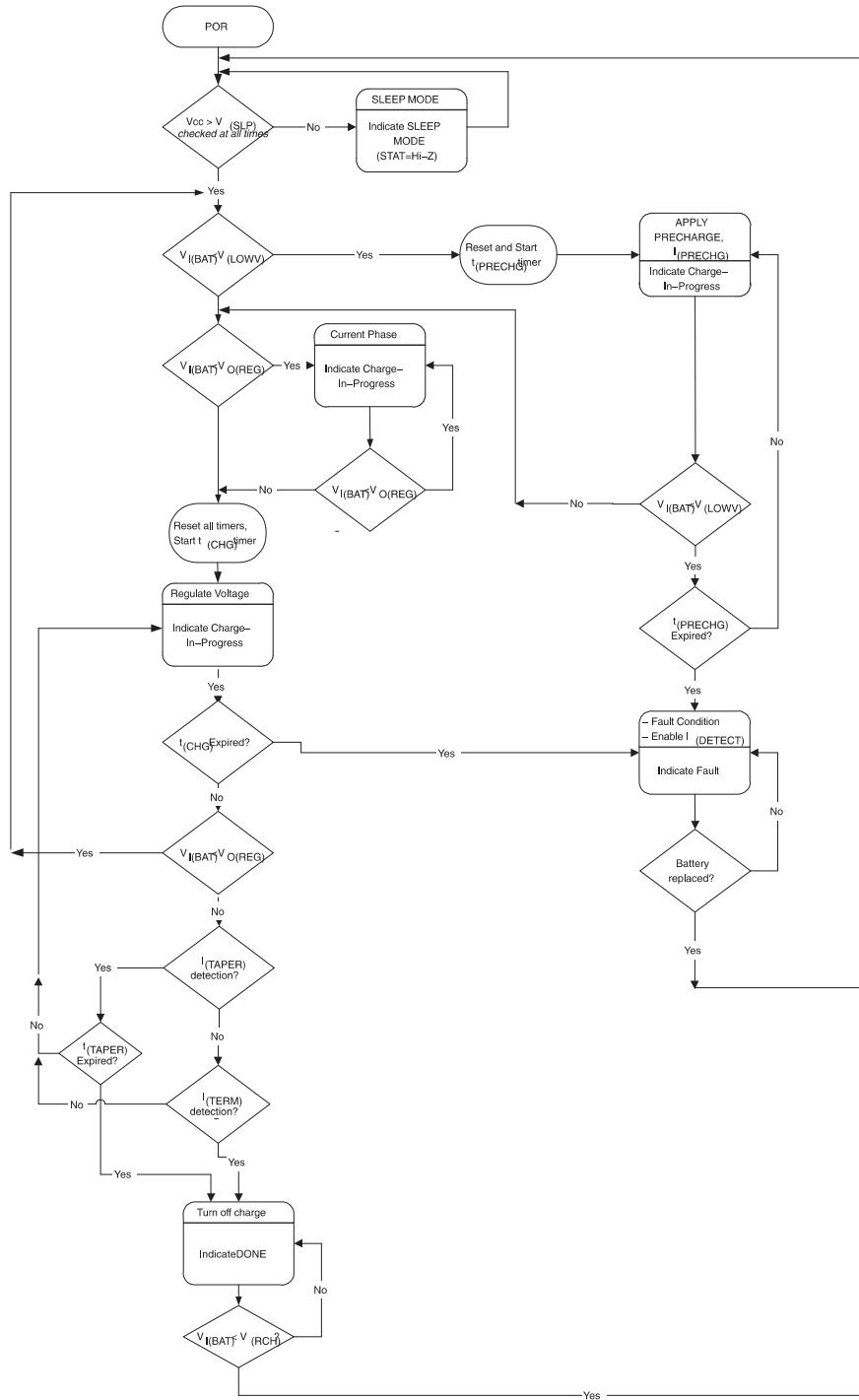


Figure 8. Operational Flow Chart

The resistor values of RT1 and RT2 are calculated by the following equations:

For NTC Thermistors:

$$R_{T1} = \frac{(5 \times RT_H \times RT_C)}{(3 \times (RT_C - RT_H))} \quad (1)$$

$$R_{T2} = \frac{(5 \times RT_H \times RT_C)}{(2 \times RT_C) - (7 \times RT_H)} \quad (2)$$

For PTC Thermisters:

$$R_{T1} = \frac{(5 \times RT_H \times RT_C)}{(3 \times (RT_H - RT_C))} \quad (3)$$

$$R_{T2} = \frac{(5 \times RT_H \times RT_C)}{(2 \times RT_H) - (7 \times RT_C)} \quad (4)$$

Where RT_C is the cold temperature resistance and RT_H is the hot temperature resistance of thermistor, as specified by the thermistor manufacturer.

R_{T1} or R_{T2} can be omitted if only one temperature (hot or cold) setting is required. Applying a voltage between the V_{TS1} and V_{TS2} thresholds to pin TS disables the temperature-sensing feature. Also applying a voltage between ($V_{CC} - 0.3$ V) and V_{CC} suspends the charge and places the IC in the low-power standby mode.

BATTERY PRE-CONDITIONING

Figure 7 shows the operational flow chart for the bq2420x.

Upon power-up, if the battery voltage is below the $V_{(LOWV)}$ threshold, the bq2420x applies a pre-charge current, $I_{(PRECHG)}$, to the battery. This feature revives deeply discharged cells. The bq2420x activates a safety timer, $t_{(PRECHG)}$, during the conditioning phase. If $V_{(LOWV)}$ threshold is not reached within the timer period, the bq2420x turns off the charger and enunciates FAULT on the STAT pin. In the case of a FAULT condition, the bq2420x reduces the current to $I_{(DETECT)}$. $I_{(DETECT)}$ is used to detect a battery replacement condition. Fault condition is cleared by POR or battery replacement.

BATTERY CHARGE CURRENT

Following a successful pre-conditioning, the bq2420x relies on an external current-limited supply to limit the charge current to the cell. The bq2420x continues this phase until the battery reaches the voltage regulation phase.

During this phase (and all other phases of operation) in order to protect the integrated powerFET, the internal short circuit and thermal protection circuits are active.

BATTERY VOLTAGE REGULATION

The voltage regulation feedback is through the BAT pin. This input is tied directly to the positive side of the battery pack. The bq2420x monitors the battery-pack voltage between the BAT and VSS pins. The bq2420x is offered in two fixed-voltage versions: 4.1 V and 4.2 V.

As a safety backup, the bq2420x also monitors the charge time in the voltage regulation mode. If taper current is not detected within this time period, $t_{(CHG)}$, the bq2420x turns off the charger and enunciates FAULT on the STAT pin. Fault condition is cleared by POR or battery replacement. Note that the safety timer is reset if the bq2420x is forced out of the voltage regulation mode.

CHARGE TERMINATION AND RECHARGE

The bq2420x monitors the charging current during the voltage regulation phase. Once the taper threshold, $I_{(TAPER)}$, is detected the bq2420x initiates the taper timer, $t_{(TAPER)}$. Charge is terminated after the timer expires. The bq2420x resets the taper timer in the event that the charge current returns above the taper threshold, $I_{(TAPER)}$.

In addition to the taper current detection, the bq2420x terminates charge in the event that the charge current falls below the $I_{(TERM)}$ threshold. This feature allows for quick recognition of a battery removal condition.

After a charge termination, the bq2420x restarts the charge once the voltage on the BAT pin falls below the $V_{(RCH)}$ threshold. This feature keeps the battery at full capacity at all times.

SLEEP MODE

The bq2420x enters the low-power sleep mode if the Vcc is removed from the circuit (i.e., the Vcc and IN pins are floating). For applications where these pins are not floating, placing a low-power $10\ \Omega$ ($1/16\ W$) between the IN and VCC pins ensures the $V_{(SLP)}$ conditions are met (see [Figure 9](#)). This feature prevents draining the battery during the absence of V_{CC} .

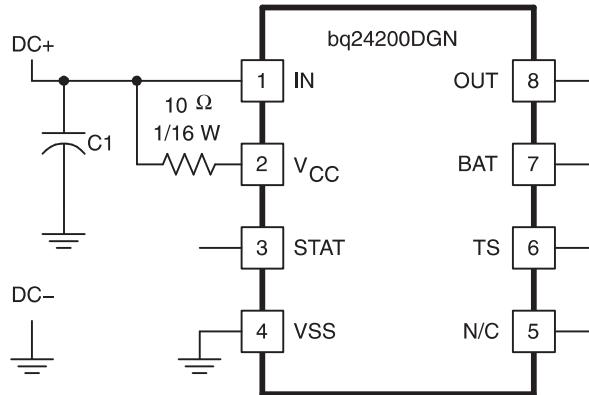


Figure 9. Sleep Mode

CHARGE ENABLE PIN

The \overline{CE} pin on bq24202, bq24203, bq24204 and bq24205 can be used to enable or suspend the charge. Charge is enabled if the voltage $V_{IL(CE)}$ is applied to the pin. Applying the $V_{IH(CE)}$ suspends the charge. During a charge suspend mode, the internal powerFET is turned off and all timers are reset.

CHARGE STATUS OUTPUT

The STAT pin on the bq2420x, indicates various conditions of operation. These conditions are summarized in [Table 1](#).

Table 1. STAT Pin

| CONDITION | STAT |
|--------------------------------------------------------------|------|
| Pre-charge | High |
| Fast-charge | High |
| Charge-complete | Low |
| Taper timer done | Low |
| Charge suspend (due to temperature or \overline{CE} input) | Hi-Z |
| Thermal shutdown | Hi-Z |
| Pre-charge timer fault | Hi-Z |
| Sleep mode | Hi-Z |
| Charge timer fault | Hi-Z |

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|-----------------------|---------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|--------------------------------------|
| BQ24200DGN | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |
| BQ24200DGNG4 | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |
| BQ24200DGNR | ACTIVE | MSOP-PowerPAD | DGN | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Purchase Samples |
| BQ24200DGNRG4 | ACTIVE | MSOP-PowerPAD | DGN | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Purchase Samples |
| BQ24201DGN | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |
| BQ24201DGNG4 | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |
| BQ24202DGN | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |
| BQ24202DGNG4 | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |
| BQ24202DGNR | ACTIVE | MSOP-PowerPAD | DGN | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Purchase Samples |
| BQ24202DGNRG4 | ACTIVE | MSOP-PowerPAD | DGN | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Purchase Samples |
| BQ24203DGN | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |
| BQ24203DGNG4 | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |
| BQ24204DGN | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |
| BQ24204DGNG4 | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |
| BQ24204DGNR | ACTIVE | MSOP-PowerPAD | DGN | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Purchase Samples |
| BQ24204DGNRG4 | ACTIVE | MSOP-PowerPAD | DGN | 8 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Purchase Samples |
| BQ24205DGN | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ | Samples (Requires Login) |
|------------------|-----------------------|---------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|--------------------------------------|
| BQ24205DGNG4 | ACTIVE | MSOP-PowerPAD | DGN | 8 | 80 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | Request Free Samples |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

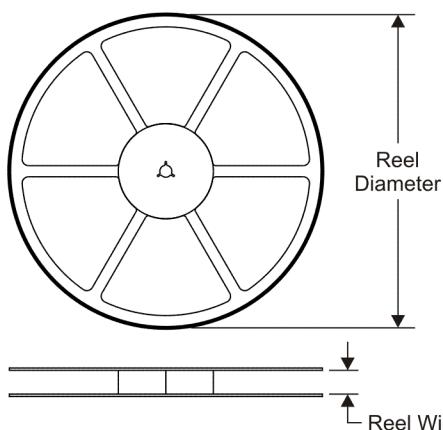
⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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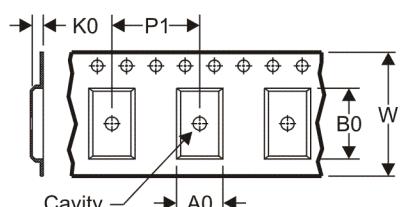
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

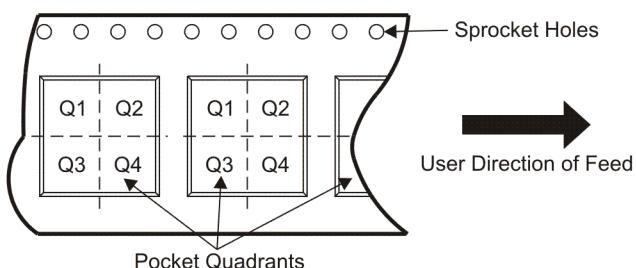


TAPE DIMENSIONS



| | |
|----|-----------------------------------------------------------|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| All dimensions are nominal | | | | | | | | | | | | | |
|----------------------------|----------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|--|
| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant | |
| BQ24200DGNR | MSOP-Power PAD | DGN | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 | |
| BQ24202DGNR | MSOP-Power PAD | DGN | 8 | 2500 | 330.0 | 12.4 | 5.3 | 3.4 | 1.4 | 8.0 | 12.0 | Q1 | |

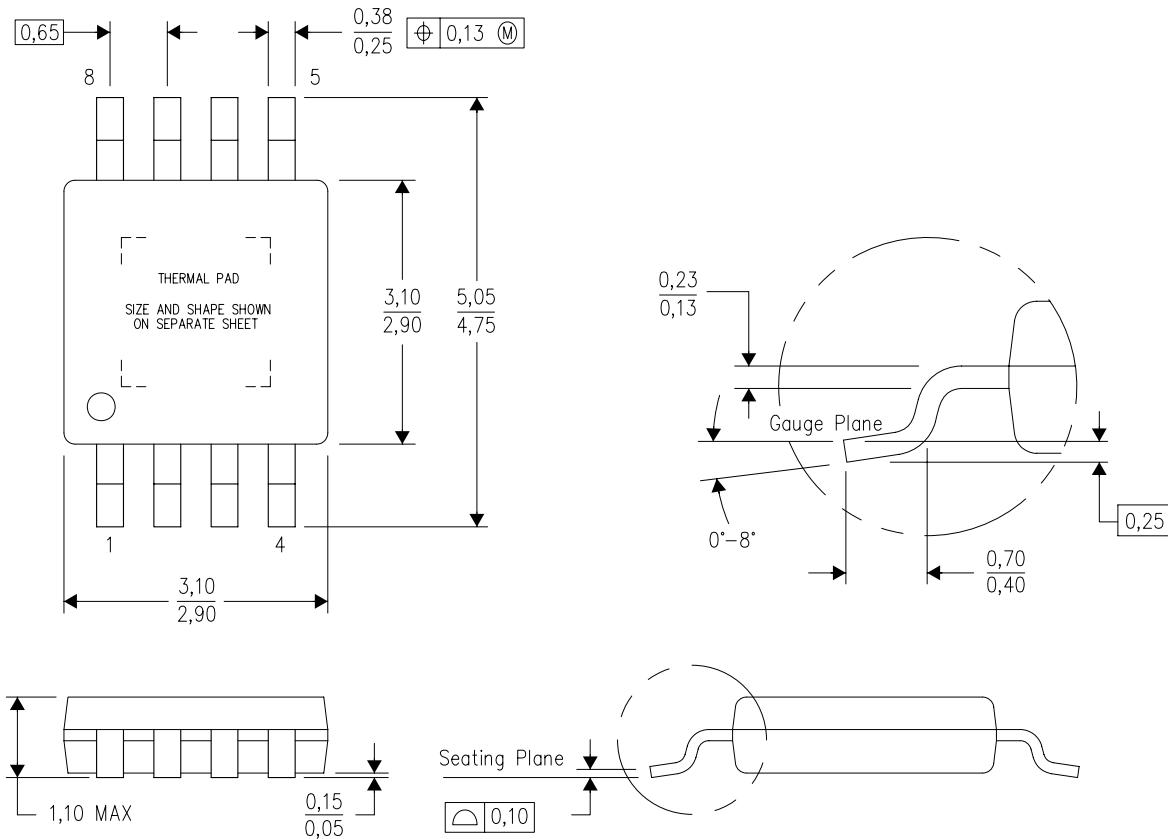
TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-------------|---------------|-----------------|------|------|-------------|------------|-------------|
| BQ24200DGNR | MSOP-PowerPAD | DGN | 8 | 2500 | 358.0 | 335.0 | 35.0 |
| BQ24202DGNR | MSOP-PowerPAD | DGN | 8 | 2500 | 358.0 | 335.0 | 35.0 |

DGN (S-PDSO-G8)

PowerPAD™ PLASTIC SMALL OUTLINE



4073271/F 05/11

NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 for information regarding recommended board layout. This document is available at www.ti.com <<http://www.ti.com>>.
- E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
- F. Falls within JEDEC MO-187 variation AA-T

PowerPAD is a trademark of Texas Instruments.

THERMAL PAD MECHANICAL DATA

DGN (S-PDSO-G8)

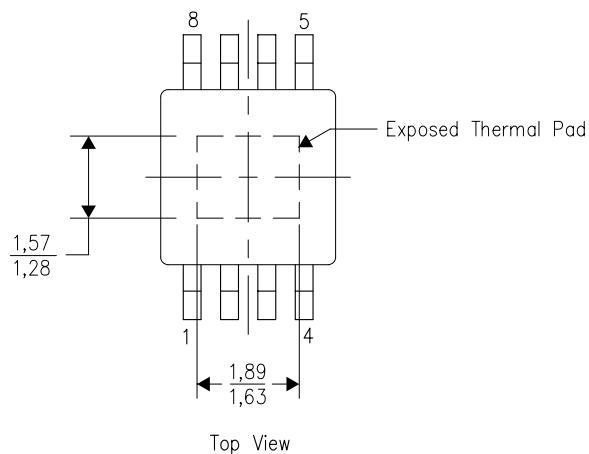
PowerPAD™ PLASTIC SMALL OUTLINE

THERMAL INFORMATION

This PowerPAD™ package incorporates an exposed thermal pad that is designed to be attached to a printed circuit board (PCB). The thermal pad must be soldered directly to the PCB. After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For additional information on the PowerPAD package and how to take advantage of its heat dissipating abilities, refer to Technical Brief, PowerPAD Thermally Enhanced Package, Texas Instruments Literature No. SLMA002 and Application Brief, PowerPAD Made Easy, Texas Instruments Literature No. SLMA004. Both documents are available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Exposed Thermal Pad Dimensions

4206323-2/H 05/11

NOTE: All linear dimensions are in millimeters

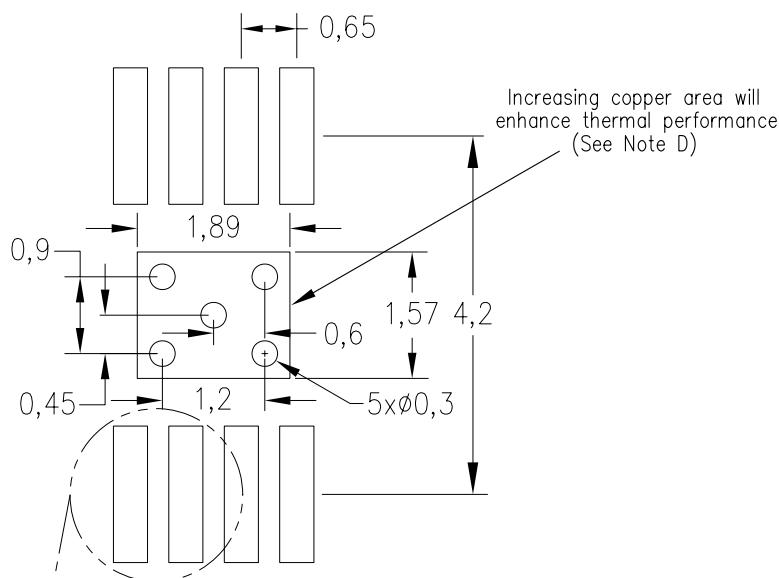
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LAND PATTERN DATA

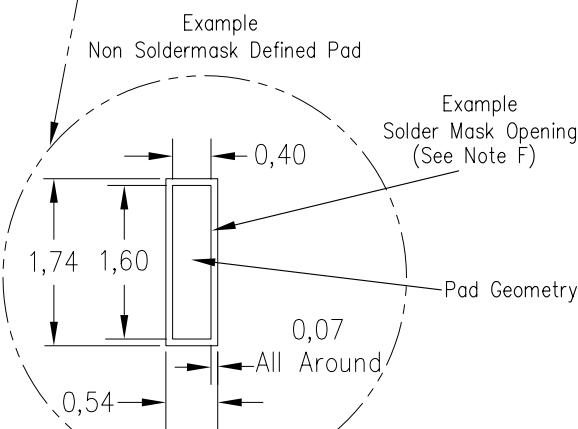
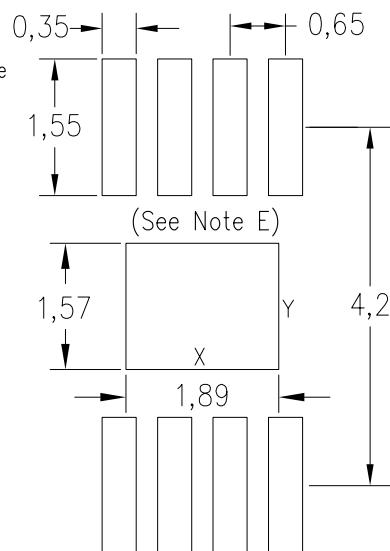
DGN (R-PDSO-G8)

PowerPAD™ PLASTIC SMALL OUTLINE

Example Board Layout
Via pattern and copper pad size
may vary depending on layout constraints



Stencil Openings
Based on a stencil thickness
of .127mm (.005inch).
Reference table below for other
solder stencil thicknesses



| Center Power Pad Solder Stencil Opening | | |
|-----------------------------------------|------|------|
| Stencil Thickness | X | Y |
| 0.1mm | 2.0 | 1.7 |
| 0.127mm | 1.89 | 1.57 |
| 0.152mm | 1.75 | 1.45 |
| 0.178mm | 1.65 | 1.35 |

4207737-2/E 04/11

NOTES:

- All linear dimensions are in millimeters.
- This drawing is subject to change without notice.
- Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
- This package is designed to be soldered to a thermal pad on the board. Refer to Technical Brief, PowerPad Thermally Enhanced Package, Texas Instruments Literature No. SLMA002, SLMA004, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>. Publication IPC-7351 is recommended for alternate designs.
- Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.
- Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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